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To: Commissioner of Patents and Trademarks
Washington, D.C. 20231

Fr: George O. Saile, Reg. No. 19,572
20 McIntosh Drive
Poughkeepsie, N.Y. 12603

Subject:

Serial No. 09/945,436 09/04/01

Jin-Yuan Lee, Mou-Shiung Lin

A METHOD FOR MAKING HIGH-
PERFORMANCE RF INTEGRATED CIRCUITS

Grp. Art Unit: 2832

INFORMATION DISCLOSURE STATEMENT

Enclosed is Form PTO-1449, Information Disclosure Citation
In An Application.

The following Patents and/or Publications are submitted to
comply with the duty of disclosure under CFR 1.97-1.99 and
37 CFR 1.56. Copies of each document is included herewith.

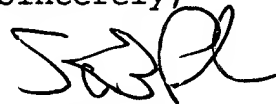
U.S. Patent 6,046,101 to Dass et al., "Passivation
Technology Combining Improved Adhesion in Passivation and a
Scribe Street Without Passivation", discloses a process where
passivation is not formed over some scribe streets.

U.S. Patent 5,904,546 to Wood et al., "Method and Apparatus for Dicing Semiconductor Wafers," discloses a dicing process on scribe lines to form planar inductors.

U.S. Patent 6,043,109 to Yang et al., "Method of Fabricating Wafer-Level Package," discloses a IC process (including inductors) where wafers are sawed on scribe lines.

U.S. Patent 5,387,551 to Mizoguchi et al., "Method of Manufacturing Flat Inductance Element," discloses an inductor process and dicing process.

Sincerely,

A handwritten signature in black ink, appearing to read 'SBA', is written over the word 'Sincerely,'.

Stephen B. Ackerman,
Reg. No. 37761